



## Material Content Data Sheet



<b>Sales Product Name</b>				BSZ100N06LS3 G		<b>Issued</b>		17. March 2016	
<b>MA#</b>				MA000522550					
<b>Package</b>				PG-TSDSON-8-2		<b>Weight*</b>		39.83 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.296	3.25	3.25	32537	32537	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		53		
	non noble metal	zinc	7440-66-6	0.008	0.02		210		
	non noble metal	iron	7439-89-6	0.168	0.42		4209		
wire	non noble metal	copper	7440-50-8	6.808	17.09	17.54	170910	175382	
	non noble metal	copper	7440-50-8	0.036	0.09	0.09	897	897	
	organic material	carbon black	1333-86-4	0.038	0.09		944		
encapsulation	plastics	epoxy resin	-	1.937	4.86		48640		
	inorganic material	silicondioxide	60676-86-0	16.835	42.29	47.24	422646	472230	
leadfinish	non noble metal	tin	7440-31-5	0.392	0.98	0.98	9841	9841	
plating	noble metal	silver	7440-22-4	0.963	2.42	2.42	24166	24166	
solder	noble metal	silver	7440-22-4	0.037	0.09		922		
	non noble metal	tin	7440-31-5	0.029	0.07		738		
	non noble metal	lead	7439-92-1	1.404	3.52	3.68	35239	36899	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		27		
	non noble metal	zinc	7440-66-6	0.004	0.01		108		
	non noble metal	iron	7439-89-6	0.086	0.22		2165		
	non noble metal	copper	7440-50-8	3.501	8.79	9.02	87898	90198	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		47		
	non noble metal	zinc	7440-66-6	0.008	0.02		189		
	non noble metal	iron	7439-89-6	0.151	0.38		3788		
	non noble metal	copper	7440-50-8	6.127	15.38	15.78	153826	157850	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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